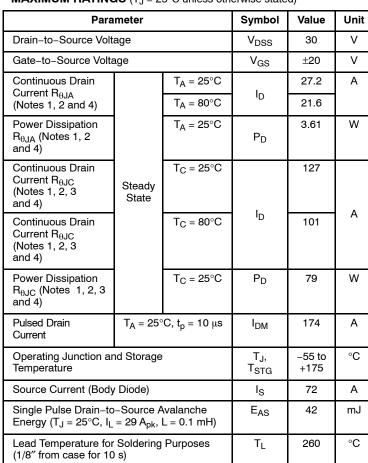
# MOSFET – Power, Single N-Channel, SO-8 FL 30 V, 127 A

#### Features

- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- NVMFS4C05NWF Wettable Flanks Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise stated)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

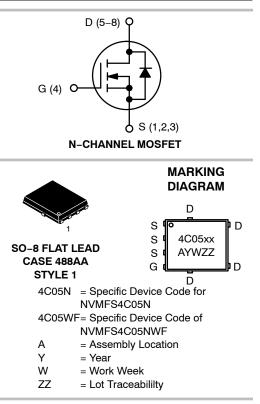
- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using 650 mm<sup>2</sup>, 2 oz Cu pad.
- Assumes heat-sink sufficiently large to maintain constant case temperature independent of device power.
- 4. Continuous DC current rating. Maximum current for pulses as long as one second is higher but dependent on pulse duration and duty cycle.



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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
30 V	2.8 mΩ @ 10 V	127 A
30 V	4.0 mΩ @ 4.5 V	127 A



#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>		
NVMFS4C05NT1G	SO–8 FL (Pb–Free)	1500 / Tape & Reel		
NVMFS4C05NT3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel		
NVMFS4C05NWFT1G	SO–8 FL (Pb–Free)	1500 / Tape & Reel		
NVMFS4C05NWFT3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	
Junction-to-Case (Drain)	$R_{ hetaJC}$	1.9	°C/W	
Junction-to-Ambient - Steady State (Note 5)	$R_{\theta JA}$	41.6	- °C/W	

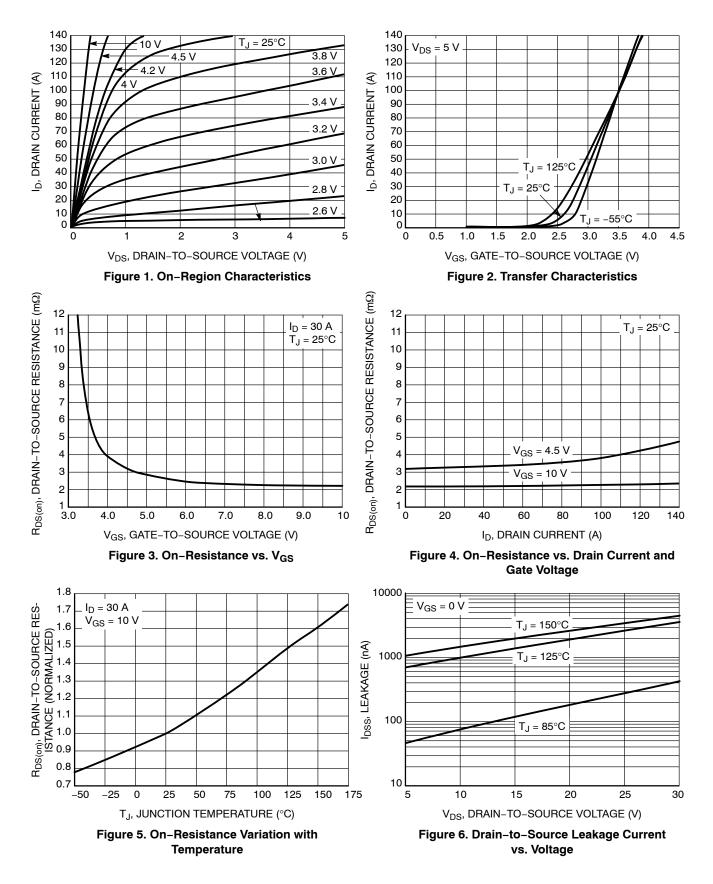
5. Surface-mounted on FR4 board using 650 mm<sup>2</sup>, 2 oz Cu pad.

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise specified)

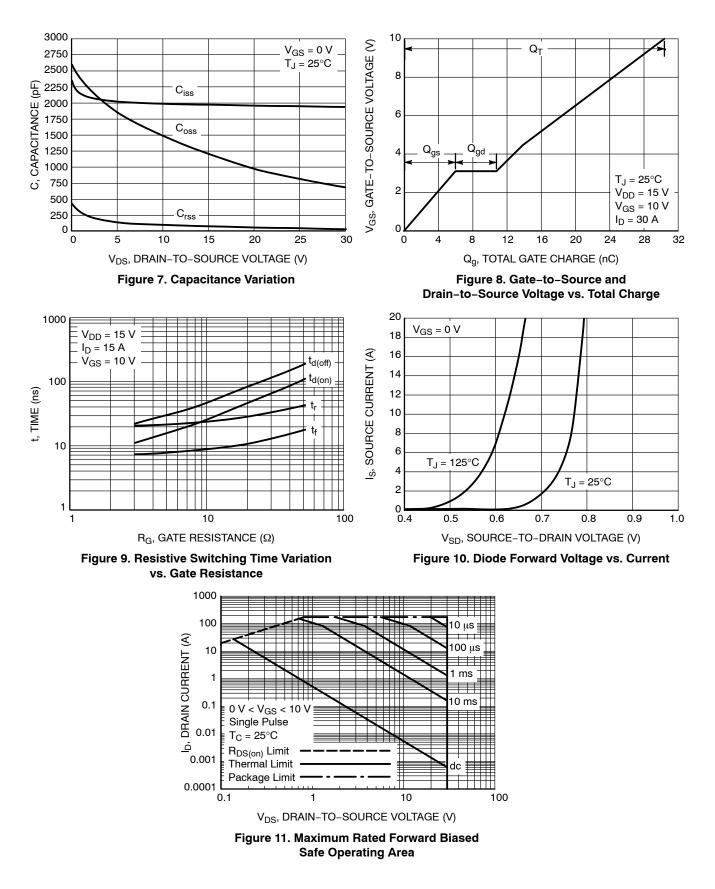
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	-				•	
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>				12		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 24 V	T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C			1.0 10	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>G</sub>	<sub>S</sub> = ±20 V			±100	nA
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub>	o = 250 μA	1.3		2.2	V
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>		-		-5.1		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A		2.3	2.8	mΩ
	20(0.1)	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 30 A		3.3	4.0	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 1.5 V, I <sub>D</sub> = 15 A			68		S
Gate Resistance	R <sub>G</sub>	T <sub>A</sub> = 25		0.3	1.0	2.0	Ω
CHARGES AND CAPACITANCES						1	
Input Capacitance	C <sub>ISS</sub>				1972		
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> = 0 V, f = 1 M	Hz, V <sub>DS</sub> = 15 V	<u> </u>	1215		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>		/ 00	<u> </u>	59		
Capacitance Ratio	C <sub>RSS</sub> /C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 15 V, f = 1 MHz			0.030		
Total Gate Charge	Q <sub>G(TOT)</sub>				14		
Threshold Gate Charge	Q <sub>G(TH)</sub>				3.3		
Gate-to-Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 15 V; I <sub>D</sub> = 30 A		<u> </u>	6.0		nC
Gate-to-Drain Charge	Q <sub>GD</sub>				5.0		1
Gate Plateau Voltage	V <sub>GP</sub>				3.1		V
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V; I <sub>D</sub> = 30 A			30		nC
SWITCHING CHARACTERISTICS (Note 7							
Turn-On Delay Time	t <sub>d(ON)</sub>			l –	11		I
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V	ns = 15 V.		32		ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>	I <sub>D</sub> = 15 A, R <sub>0</sub>	<sub>a</sub> = 3.0 Ω		21		
Fall Time	t <sub>f</sub>				7.0		
Turn-On Delay Time	t <sub>d(ON)</sub>				8.0		1
Rise Time	t <sub>r</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 15 V, $I_{D}$ = 15 A, $R_{G}$ = 3.0 $\Omega$			26		ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>				26		
Fall Time	t <sub>f</sub>				5.0		
DRAIN-SOURCE DIODE CHARACTERIS	STICS					-	
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C	1	0.77	1.1	
		I <sub>S</sub> = 10 A	T <sub>J</sub> = 125°C		0.62		V
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dI <sub>S</sub> /dt = 100 A/µs, I <sub>S</sub> = 30 A			40.2		ns
Charge Time	t <sub>a</sub>				20.3		
Discharge Time	t <sub>b</sub>			<u> </u>	19.9		
Reverse Recovery Charge	Q <sub>RR</sub>			<u> </u>	30.2		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 6. Pulse Test: pulse width  $\leq$  300 µs, duty cycle  $\leq$  2%. 7. Switching characteristics are independent of operating junction temperatures.

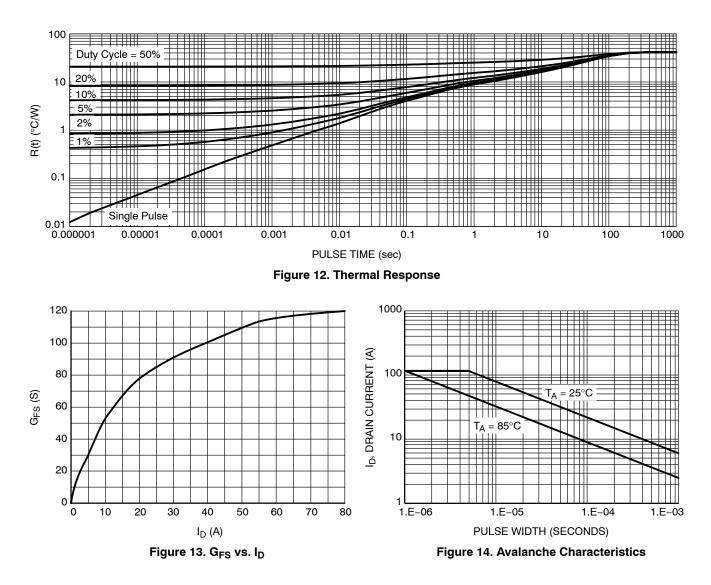
#### **TYPICAL CHARACTERISTICS**



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## **TYPICAL CHARACTERISTICS**







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